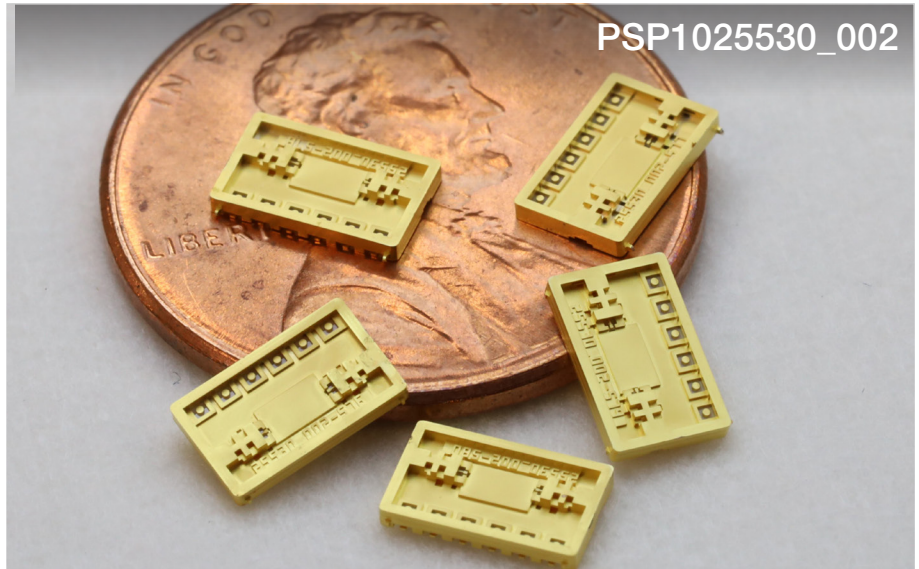


Features and Benefits

- Ultra-Low Loss; less than 0.15 dB insertion loss from DC to 21 GHz
- Ideal thermal performance due to solid copper construction
- Chip interface compatible with automated Au wire bonding
- PCB interface compatible with standard SMT processes

Applications

- Military
- Space
- Communications
- Instrumentation

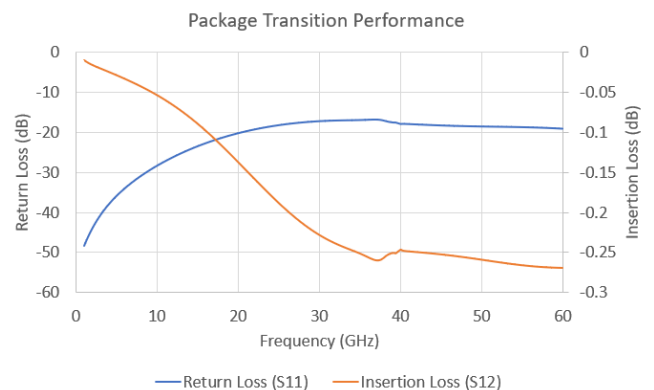
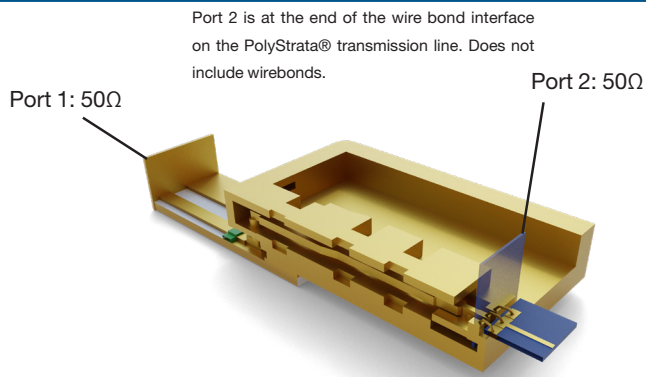


PolyStrata® Package

Market-leading lowest noise figure, surface mount form factor package.

Cubic Nuvotronics presents a new state of the art Low Loss MMIC package. The PolyStrata® package complements integrated MMIC performance, with less than 0.3 dB insertion loss up to 60 GHz and 15 dB return loss. The package can be surface mounted to a PCB using standard SMT processes. This increases the ease of manufacturing while maintaining superior performance in a smaller size compared to other packaging substrates.

Typical Electrical Performance



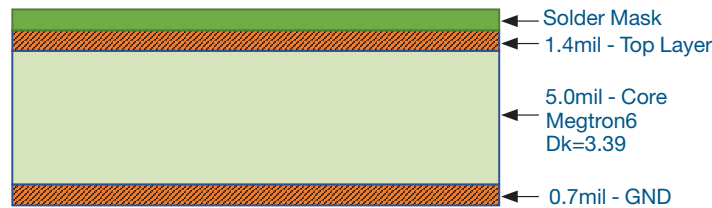
Additional Details

Special Handling / Storage Instructions (Substrate Only)	
Storage	Per JEP160 - Oxygen Sensitive Devices
EDS Sensitivity	None
Moisture Sensitivity	MSL1, 168 hrs., 85C/85RH, 3x solder reflow
Component Termination Finish	Immersion Gold over Immersion Silver
Packaging Available	Gel-Pak®, Tape and Reel
Ordering Part Number	PSP1025530_002
Export Classification	EAR99
Lid Options	Compatible with metal or plastic lids, and most lid-sealing processes

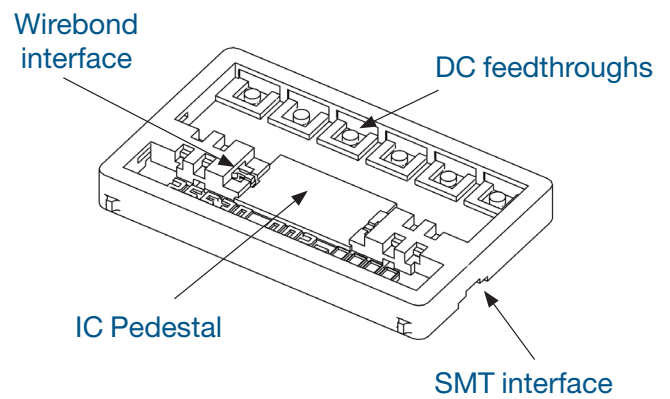
Absolute Maximum Ratings

Current	2.0 amps
Operating Temp	-55°C to 125°C
Solder Reflow	Compatible with JEDEC J-STD-020
Epoxy Attach	150°C max. for 90 minutes

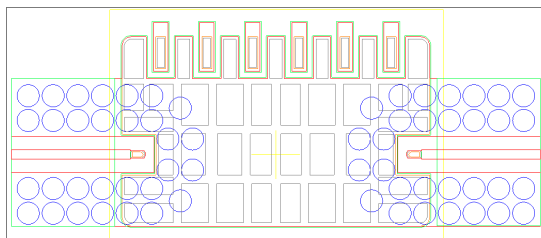
PCB Stack-up View



Component View



PCB Layout



- Legend:
- TOP COPPER ■
 - TOP PASTE ■
 - TOP MASK ■
 - VIAS ■
 - PART KEEP OUT ■
 - PACKAGE FOOTPRINT ■

3D models, S-parameters, board footprint DXF drawings available on request

Mechanical Drawing

